

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	61	(((\$plating electroplat\$5) same ((revers\$4 forward pulse period\$4) near10 current)) and ((direct DC) near5 current) and (electropolish\$5 electrochemical adj polish\$3) and copper and (wafer semiconductor chip circuit)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/04 10:12
L2	12	("205"/\$.ccls. "204"/\$.ccls.) and surface near3 roughness and (electropolish\$5 electrochemical adj polish\$3) and trace and (wafer semiconductor chip circuit) and ((board printed) near4 circuit)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/04 13:58
L3	12	("20020060090" "20020155021" "20030006063" "20030096082" "20030108766" "6476330").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/04 10:26
L4	0	("205"/\$.ccls. "204"/\$.ccls.) and surface near3 roughness and (electropolish\$5 electrochemical adj polish\$3) and skin near4 effect and ((board printed) near4 circuit)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/04 11:40
L5	1	surface near3 roughness and (electropolish\$5 electrochemical adj polish\$3) and skin near4 effect and ((board printed) near4 circuit)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/04 11:42
L6	77	surface near3 roughness and skin near4 effect and ((board printed) near4 circuit)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/04 11:42
L7	60	surface near3 roughness and skin near4 effect and ((board printed) near4 circuit) and (\$plating electroplat\$5)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/04 11:42
L8	2	("6309528").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/04 13:58